

ABSTRACT DEADLINE EXTENDED: November 22, 2019

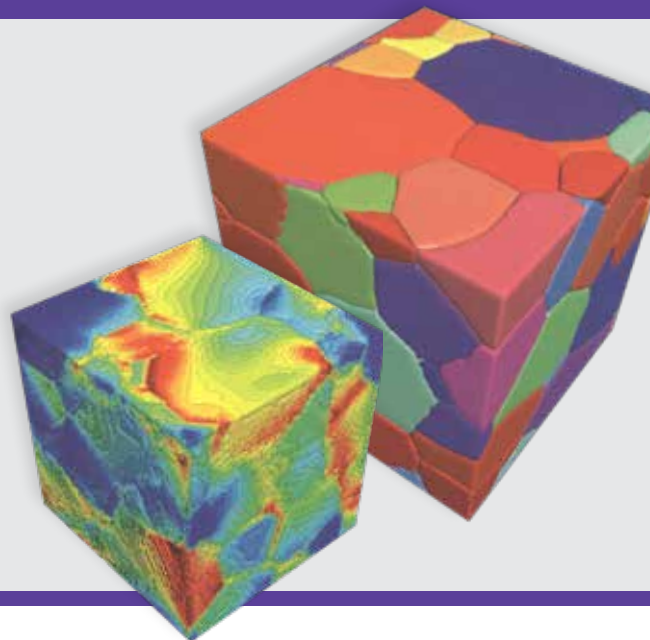
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June 28-July 1, 2020

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